Abstracts

K-band receiver front-end IC integrating micromachined filter and flip-chip assembled active devices

K. Takahashi, S. Fujita, U. Sangawa, A. Ono, T. Urabe, S. Takeyama, H. Ogura and H. Yabuki. "K-band receiver front-end IC integrating micromachined filter and flip-chip assembled active devices." 1999 MTT-S International Microwave Symposium Digest 99.1 (1999 Vol. I [MWSYM]): 229-232 vol.1.

A novel three-dimensional K-band receiver front-end IC was developed in which a micromachined low-loss filter and flip-chip devices ware integrated on a silicon substrate. An inverted microstrip line and a new resonator are newly introduced in the filter. Multilayered BCB and flip-chip bonding technologies are also adopted.

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